



Designation: F2678 – 10

Standard Practice for Preparing Panel Underlayments, Thick Poured Gypsum Concrete Underlayments, Thick Poured Lightweight Cellular Concrete Underlayments, and Concrete Subfloors with Underlayment Patching Compounds to Receive Resilient Flooring¹

This standard is issued under the fixed designation F2678; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon (ϵ) indicates an editorial change since the last revision or reapproval.

1. Scope

1.1 This practice includes recommendations for preparing and smoothing panel underlayments, gypsum concrete and concrete subfloors with patching compounds upon which resilient flooring may be installed.

1.2 This practice does not cover the adequacy of the subfloor assembly to perform its structural requirements, which is governed by local building codes.

1.3 This practice does not supersede in any manner the resilient flooring, underlayment or adhesive manufacturer's written instructions. Consult the individual resilient flooring, underlayment or adhesive manufacturer for specific recommendations.

1.4 The values stated in inch-pound units are to be regarded as standard. The values given in parentheses are mathematical conversions to SI units that are provided for information only and are not considered standard.

1.5 *This standard does not purport to address all of the safety concerns, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.*

2. Referenced Documents

2.1 *ASTM Standards:*²

[C109/C109M Test Method for Compressive Strength of Hydraulic Cement Mortars \(Using 2-in. or \[50-mm\] Cube Specimens\)](#)

¹ This practice is under the jurisdiction of ASTM Committee F06 on Resilient Floor Coverings and is the direct responsibility of Subcommittee F06.40 on Practices.

Current edition approved June 1, 2010. Published August 2010. DOI: 10.1520/F2678-10.

² For referenced ASTM standards, visit the ASTM website, www.astm.org, or contact ASTM Customer Service at service@astm.org. For *Annual Book of ASTM Standards* volume information, refer to the standard's Document Summary page on the ASTM website.

[C472 Test Methods for Physical Testing of Gypsum, Gypsum Plasters and Gypsum Concrete](#)

[F141 Terminology Relating to Resilient Floor Coverings](#)

[F710 Practice for Preparing Concrete Floors to Receive Resilient Flooring](#)

[F1482 Practice for Installation and Preparation of Panel Type Underlayments to Receive Resilient Flooring](#)

[F2419 Practice for Installation of Thick Poured Gypsum Concrete Underlayments and Preparation of the Surface to Receive Resilient Flooring](#)

[F2471 Practice for Installation of Thick Poured Lightweight Cellular Concrete Underlayments and Preparation of the Surface to Receive Resilient Flooring](#)

3. Terminology

3.1 Definitions used in this practice shall be in accordance with Terminology [F141](#).

4. Significance and Use

4.1 This practice provides minimum recommendations for preparing and smoothing panel underlayments, thick poured gypsum concrete underlayments, thick poured lightweight cellular concrete underlayments and concrete subfloors with patching compounds. Actual requirements for materials to be used, mixtures, and other details are generally included as part of the project plans or specification details and may vary from the minimum recommendations set forth in this practice.

5. Product Requirements

5.1 The patching compound shall be able to be applied from featheredge up to the manufacturer's specified thickness over large areas.

5.2 The patching compound may require the addition of an additive other than water.

5.3 The patching compound shall be able to be covered by resilient floorings as soon as the patching hardens and dries sufficiently.

5.4 The dried patching compound shall be moisture-free, mildew-resistant and alkali-resistant.

5.5 For commercial installations, the patching compound shall develop a minimum of 3000 psi compressive strength after 28 days when tested in accordance with Test Method **C109/C109M** (air-cured only) or with Test Methods **C472**.

6. Material Acceptance

6.1 All patching compounds shall be delivered in their original, factory packaging.

7. Material Storage, Conditioning and Protection

7.1 All patching compounds shall be kept dry in a temperature controlled environment on site and protected from the weather at least 48 h prior to use. The temperature shall not be below 65°F (18°C) or above 100°F (38°C). Refer to the patching compound manufacturer's recommendation for more specific instruction.

7.2 All patching compounds shall be kept off the ground and away from damp and cold surfaces.

7.3 Protect the applied patching compound from excessive heat and drafty conditions while curing.

7.4 Protect the applied patching compound and the entire subfloor from traffic, dirt or dust or other contaminants such as sweeping compounds until final installation of the resilient floor covering.

8. General Guidelines

8.1 General Specifications:

8.1.1 The patching compound shall not be applied to a subfloor containing frost. The subfloor surface temperature shall not be below 50°F (10°C) or above 95°F (35°C). The temperature conditions for installing resilient flooring products and the patching compound is typically 65 to 85°F (18 to 30°C) for 48 h before, during and after the installation. The complete installation shall remain within the range of 55 to 95°F (13 to 35°C) thereafter.

8.1.2 All subfloors shall be clean and free of dust, oil, grease, paint, tar, wax, curing compounds, sealers, from release agents, primers, free alkali, loosely bonded toppings, loose particles, old adhesive residues and any other substance that may prevent or reduce adhesion of the patching compound.

8.1.3 Any substance that may reduce or prevent the adhesion from the subfloor shall be completely removed by mechanical means only. Refer to supplementary requirement section.

8.1.4 Structural lightweight concretes having a minimum density of 115 lb/ft³ (1842 kg/m³) and a minimum compressive strength of 3000 psi can be suitable substrates to receive patching compounds.

8.1.5 The temperature of a heated subfloor must not exceed 85°F (30°C).

8.1.6 All moving joints such as expansion joints, isolation joints and any cracks exhibiting movement shall not be filled with patching compound or covered with resilient flooring. Consult the resilient flooring manufacturer regarding the use of an expansion joint covering system.

8.2 Panel Underlayment:

8.2.1 All panel underlayment used shall be recommended by either the panel underlayment manufacturer or the resilient flooring manufacturer.

8.2.2 All panel underlayment shall be installed in accordance with the Standard Practice **F1482**.

8.2.3 All wood structural panel floor assemblies shall be double-layered. The subfloor panel shall be 5/8 in. (16 mm) thick minimum wood structural panels (usually Exterior Grade Plywood) over joist 16 in. (41 cm), typically on center. Joist center spacing shall comply with local building codes. The second layer shall be a minimum 1/4 in. (6.4 mm) thick, and sufficiently smooth to receive resilient flooring (thicker boards may be required for commercial applications). The adjacent edges of the underlayment panels shall not be more than 1/32 in. (1.6 mm) above or below each other. End joints of panel underlayment shall be offset from subfloor panel joints by at least one joist spacing. Panel underlayment edge joints shall be offset from subfloor panel edge joints by at least 2 in.

8.3 Concrete Subfloors:

8.3.1 All concrete subfloors shall meet the requirements outlined in Practice **F710**.

8.3.2 All concrete subfloors shall have a minimum density of 115 lb/ft³ (1842 kg/m³).

8.3.3 Due to the varying porosity of concrete subfloors, we recommend that a bond test be performed to ensure adequate bond. If an adequate bond is not achieved, abrasively prepare the concrete subfloor surface according to the patching compound manufacturer's recommendation. Methods such as grinding or shot blasting are appropriate.

8.3.4 Porous concrete substrate may require being primed. Refer to the patching compound manufacturer's recommendation.

8.4 Gypsum Concrete Subfloors:

8.4.1 All gypsum concrete subfloors shall meet the requirements outlined in Practice **F2419**.

8.4.2 All gypsum concrete subfloors shall have a minimum density of 105 lb/ft³ (1460 kg/m³).

8.4.3 Porous gypsum concrete substrates may require being primed. Refer to the patching compound manufacturer's recommendation.

8.4.4 Due to the varying porosity of gypsum concrete subfloors, we recommend that a bond test be performed to ensure adequate bond. If an adequate bond is not achieved, refer to the patching compound manufacturer's recommendation.

8.5 Poured Lightweight Cellular Concrete Subfloors:

8.5.1 All poured lightweight cellular concrete subfloors shall meet the requirements outlined in Practice **F2471**.

8.5.2 All poured lightweight cellular concrete subfloors shall have a minimum density of 110 lb/ft³ (1762 kg/m³).

8.5.3 Porous poured lightweight cellular concrete substrate may require being primed. Refer to the patching compound manufacturer's recommendation.

8.5.4 Due to the varying porosity of poured lightweight cellular concrete subfloors, we recommend that a bond test be